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FOR IMMEDIATE RELEASE

MIRTEC Brings Next-Gen 3D Inspection Innovation to SMTA Guadalajara 2026

September 2026 – MIRTEC, the ‘Global Leader in Inspection Technology’, announced its participation in the SMTA Guadalajara 2026, taking place October 7–8, 2026 at Expo Guadalajara, Mexico. During the event, MIRTEC will showcase its full portfolio of advanced 3D Automated Optical Inspection (AOI), Solder Paste Inspection (SPI), and Smart Factory Automation solutions—specifically designed to meet the demanding inspection requirements of the electronics manufacturing industry. Attendees are invited to visit MIRTEC’s booth 302 and experience firsthand the company’s commitment to innovation, quality, and productivity.

Key Inspection Systems on Display:

MV-6TB

The MV-6TB simultaneous Top/Bottom AOI system inspects both sides of the PCB in a single pass, eliminating sequential inspection. Its Dual PC Architecture processes top and bottom inspection data independently, maintaining performance while reducing cycle time and improving productivity by up to 200%. This helps manufacturers shorten tact time and increase line throughput.

GENESYS-CC

The GENESYS-CC improves coating visibility, defect detection, and process reliability through coaxial, vertical, and angled UV illumination for shadow-free image acquisition. 18MP side cameras extend inspection to component sides, connectors, J-leads, splatters, bubbles, and cracks. With 65MP / 4.3µm imaging, AI-based 30µm micro-bubble detection, thickness measurement from 20µm to 8,000µm depending on configuration, and internal flipper support, it delivers comprehensive conformal coating inspection.

MV-6 OMNI Alpha

The MV-6 Alpha combines MIRTEC’s proven 3D AOI technology with stable and cost-effective SMT inspection. Its 12-projection blue-light moiré system and 8-phase coaxial color lighting provide precise 3D measurement across diverse PCB conditions. AI auto teaching, dedicated THT algorithms, optional 45mm Z-axis inspection, 18MP side cameras, and an internal flipper expand coverage for tall components, side features, OCR, and double-sided PCBs.

MS-11 Alpha

The MS-11 Alpha is a premium 3D SPI system designed for stable, high-precision solder paste inspection at a competitive cost. Its DLP-based optics, 25MP camera, large FOV, and telecentric lens improve measurement consistency while reducing inspection time. The optional





Solder Supplement Function automatically corrects insufficient or missing solder to reduce defects and improve process efficiency.

INTELLI-PRO AI

INTELLI-PRO AI connects inspection, monitoring, and production management across the SMT line for a fully integrated smart factory. AI-based auto teaching, inspection, and defect classification reduce programming time by up to 90%, while on-site AI training improves accuracy using real production data. Real-time SPC, remote debugging, TRMS-based centralized management, and integrated SPI/AOI data support process stability, defect traceability, and faster root-cause analysis.

Commitment to Smart Manufacturing

“MIRTEC remains committed to helping electronics manufacturers achieve higher quality, greater productivity, and more intelligent production through advanced AOI, SPI, and Smart Factory technologies,” said a Fernando Islas. “With our expanding presence in Mexico, we look forward to meeting customers and partners at Booth 302 and demonstrating how MIRTEC’s AI-driven inspection and process solutions can support real-world manufacturing challenges.”

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MIRTEC is a leading global supplier of automated inspection systems for the electronics manufacturing industry. For more information about MIRTEC’s innovative inspection solutions and their participation in SMTA Guadalajara 2026, please visit www.mirtec.com